



9. COPPER THEFTING MUST BE ADDED TO ANY DESIGN BUT MUST MAINTAIN 100 MILS CLEAR TO ANY EXISTING FEATURE.
16. REGARDLESS OF CAD DATA VENDOR TO INSURE THAT ALL VIAS UNDER BGA ARE COVERED WITH SOLDERMASK.
15. THIS IS A CONTROLLED IMPEDANCE DESIGN. VENDOR TO ADJUST TRACE WIDTH AND/OR LAYER STACK TO ACHIEVE IMPEDANCE SHOWN IN TABLE.
14. PACKAGING OF FINISHED BOARDS TO BE MARKED WITH AN APPROVED Pb FREE LABEL.
13. CERTIFICATE OF COMPLIANCE TO BE PROVIDED ON ALL SHIPMENTS.
12. EACH LOT MUST INCLUDE ONE SOLDER SAMPLE.
11. BOARDS TO BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED NETLIST.
10. FABRICATE PER IPC-6012, CLASS II.
9. ACCEPTABILITY CRITERIA TO BE PER IPC-A-600, LATEST ISSUE.
8. VENDORS UL ID, RECOGNIZED COMPONENT SYMBOL, 94V-0 RATING PER UL796 AND DATE CODE TO APPEAR IN THIS AREA ONLY ON FAR SIDE.
7. FABRICATION DRAWING TAKES PRECEDENCE OVER ARTWORK AND/OR PURCHASE ORDER(S).
6. SURFACE FINISH TO BE ELECTROLESS NICKEL IMMERSION GOLD (ENIG) WITH 2-8 MICROINCH GOLD OVER 100-150 MICROINCH NICKEL OVER COPPER ON ALL EXPOSED PADS.
5. FINISHED COPPER THICKNESS TO BE PER LAYER DETAIL.
4. SILK SCREEN LEGEND TO BE WHITE, NON-CONDUCTIVE EPOXY INK.
3. GREEN SOLDER MASK BOTH SIDES LPI (LIQUID PHOTO-IMAGEABLE) PER IPC-SM-840.
2. MATERIAL TO BE HIGH Tg FR 370HR OR EQUIV. PER IPC, GREEN OR NATURAL, MUST MEET RoHS ASSEMBLY PROCESS REQUIREMENTS. OVERALL THICKNESS TO BE PER LAYER DETAIL.
1. THICKNESS: XX=+/-0.03; XXX=+/-0.05.

NOTES: UNLESS OTHERWISE SPECIFIED

LAYER DETAIL

NOTE: TRACE WIDTHS/LAYERS SHOWN FOR REFERENCE
MAY NOT APPEAR ON ALL LAYERS AS SHOWN

	SE	DIFF PAIR	DIFF PAIR	REF PLANE
LAYER	50 OHMS +/-10% LW (MILS)	90 OHMS +/-10% LW (MILS)	100 OHMS +/-10% LW/GAP (MILS)	
L1 PRIMARY SIDE	6.75	5.30/4.70	5.00/7.00	2
L2 GND PLANE	NA	NA	NA	NA
L3 SIG PLANE	6.30	5.30/4.70	NA	2/4
L4 PWR PLANE	NA	NA	NA	NA
L5 GND PLANE	NA	NA	NA	NA
L6 PWR PLANE	NA	NA	NA	NA
L7 SIGNAL	6.50	NA	NA	6/9
L8 SIGNAL	6.30	NA	NA	6/9
L9 GND PLANE	NA	NA	NA	NA
L10 SECONDARY	6.75	NA	NA	9

INTERPRET PER ASME Y14.5M-1994

DWG. NO.	REV
PC-104 CARTRIDGE BOARD	2.9